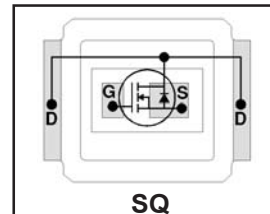


DirectFET® Power MOSFET ②

- RoHS Compliant and Halogen Free ①
- Low Profile (<0.7 mm)
- Dual Sided Cooling Compatible ①
- Ultra Low Package Inductance
- Optimized for High Frequency Switching ①
- Ideal for CPU Core DC-DC Converters
- Optimized for Control FET application ①
- Low Conduction and Switching Losses
- Compatible with existing Surface Mount Techniques ①
- 100% Rg tested

Typical values (unless otherwise specified)

V_{DS}	V_{GS}	$R_{DS(on)}$	$R_{DS(on)}$		
30V max	±20V max	5.1mΩ @ 10V	8.5mΩ @ 4.5V		
$Q_{g\ tot}$	Q_{gd}	Q_{gs2}	Q_{rr}	Q_{oss}	$V_{gs(th)}$
9.2nC	3.0nC	1.2nC	19nC	7.9nC	1.9V



Applicable DirectFET Outline and Substrate Outline (see p.7,8 for details) ①

SQ	SX	ST		MQ	MX	MT	MP			
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Description

The IRF8327SPbF combines the latest HEXFET® Power MOSFET Silicon technology with the advanced DirectFET® packaging to achieve the lowest on-state resistance in a package that has the footprint of a MICRO-8 and only 0.7 mm profile. The DirectFET® package is compatible with existing layout geometries used in power applications, PCB assembly equipment and vapor phase, infra-red or convection soldering techniques, when application note AN-1035 is followed regarding the manufacturing methods and processes. The DirectFET® package allows dual sided cooling to maximize thermal transfer in power systems, improving previous best thermal resistance by 80%.

The IRF8327SPbF balances both low resistance and low charge along with ultra low package inductance to reduce both conduction and switching losses. The reduced total losses make this product ideal for high efficiency DC-DC converters that power the latest generation of processors operating at higher frequencies. The IRF8327SPbF has been optimized for parameters that are critical in synchronous buck operating from 12 volt bus converters including Rds(on) and gate charge to minimize losses.

Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRF8327STRPbF	DirectFET SQ	Tape and Reel	4800	"TR" suffix
IRF8327STR1PbF	DirectFET-SQ	Tape and Reel	1000	"TR1" suffix EOL notice # 264

Absolute Maximum Ratings

Parameter	Max.	Units
V_{DS} Drain-to-Source Voltage	30	V
V_{GS} Gate-to-Source Voltage	±20	V
$I_D @ T_A = 25^\circ C$ Continuous Drain Current, $V_{GS} @ 10V$ ③	14	A
$I_D @ T_A = 70^\circ C$ Continuous Drain Current, $V_{GS} @ 10V$ ③	11	A
$I_D @ T_C = 25^\circ C$ Continuous Drain Current, $V_{GS} @ 10V$ ④	60	A
I_{DM} Pulsed Drain Current ⑤	110	A
E_{AS} Single Pulse Avalanche Energy ⑥	62	mJ
I_{AR} Avalanche Current ⑤	11	A

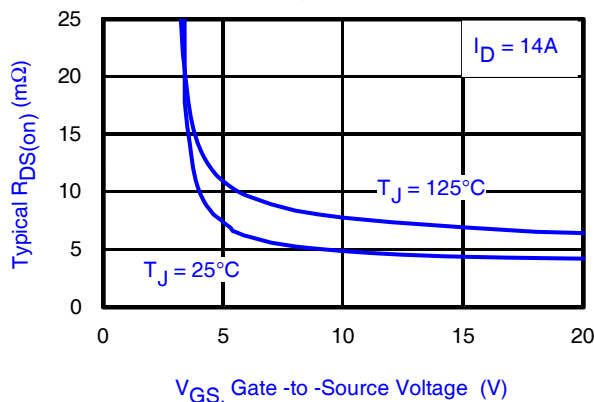


Fig 1. Typical On-Resistance vs. Gate Voltage

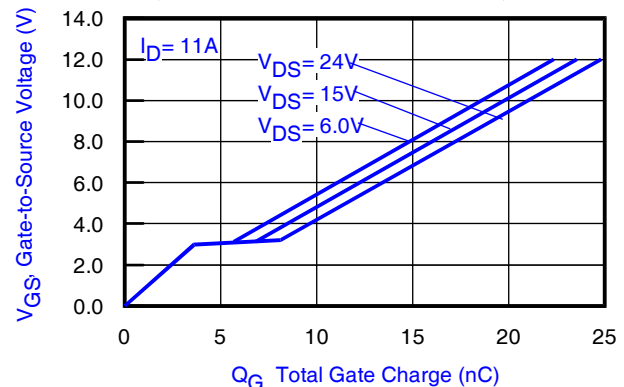


Fig 2. Typical Total Gate Charge vs. Gate-to-Source Voltage

Notes:

- ① Click on this section to link to the appropriate technical paper.
- ② Click on this section to link to the DirectFET Website.
- ③ Surface mounted on 1 in. square Cu board, steady state.

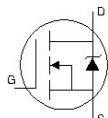
- ④ T_C measured with thermocouple mounted to top (Drain) of part.
- ⑤ Repetitive rating; pulse width limited by max. junction temperature.
- ⑥ Starting $T_J = 25^\circ C$, $L = 1.1mH$, $R_G = 25\Omega$, $I_{AS} = 11A$.

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	30	—	—	V	V _{GS} = 0V, I _D = 250μA
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	22	—	mV/°C	Reference to 25°C, I _D = 1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance	—	5.1	7.3	mΩ	V _{GS} = 10V, I _D = 14A ⑦
		—	8.5	10.9		V _{GS} = 4.5V, I _D = 11A ⑦
V _{GS(th)}	Gate Threshold Voltage	1.4	1.9	2.4	V	V _{DS} = V _{GS} , I _D = 25μA
ΔV _{GS(th)} /ΔT _J	Gate Threshold Voltage Coefficient	—	-6.3	—	mV/°C	
I _{DSS}	Drain-to-Source Leakage Current	—	—	1.0	μA	V _{DS} = 24V, V _{GS} = 0V
		—	—	150		V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V _{GS} = 20V
	Gate-to-Source Reverse Leakage	—	—	-100		V _{GS} = -20V
g _{fs}	Forward Transconductance	25	—	—	S	V _{DS} = 15V, I _D = 11A
Q _g	Total Gate Charge	—	9.2	14	nC	V _{DS} = 15V V _{GS} = 4.5V I _D = 11A See Fig. 15
Q _{gs1}	Pre-V _{th} Gate-to-Source Charge	—	2.7	—		
Q _{gs2}	Post-V _{th} Gate-to-Source Charge	—	1.2	—		
Q _{gd}	Gate-to-Drain Charge	—	3.0	—		
Q _{godr}	Gate Charge Overdrive	—	2.3	—		
Q _{sw}	Switch Charge (Q _{gs2} + Q _{gd})	—	4.2	—		
Q _{oss}	Output Charge	—	7.9	—	nC	V _{DS} = 16V, V _{GS} = 0V
R _G	Gate Resistance	—	2.1	3.7	Ω	
t _{d(on)}	Turn-On Delay Time	—	7.8	—	ns	V _{DD} = 15V, V _{GS} = 4.5V ⑦ I _D = 11A R _G = 1.8Ω See Fig. 17
t _r	Rise Time	—	8.9	—		
t _{d(off)}	Turn-Off Delay Time	—	9.3	—		
t _f	Fall Time	—	5.3	—		
C _{iss}	Input Capacitance	—	1430	—	pF	V _{GS} = 0V V _{DS} = 15V f = 1.0MHz
C _{oss}	Output Capacitance	—	370	—		
C _{rss}	Reverse Transfer Capacitance	—	140	—		

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	—	—	52	A	MOSFET symbol showing the integral reverse p-n junction diode.
I _{SM}	Pulsed Source Current (Body Diode) ⑤	—	—	110		
V _{SD}	Diode Forward Voltage	—	0.80	1.0	V	T _J = 25°C, I _S = 11A, V _{GS} = 0V ⑦
t _{rr}	Reverse Recovery Time	—	17	26	ns	T _J = 25°C, I _F = 11A
Q _{rr}	Reverse Recovery Charge	—	19	29	nC	di/dt = 230A/μs ⑦


Notes:

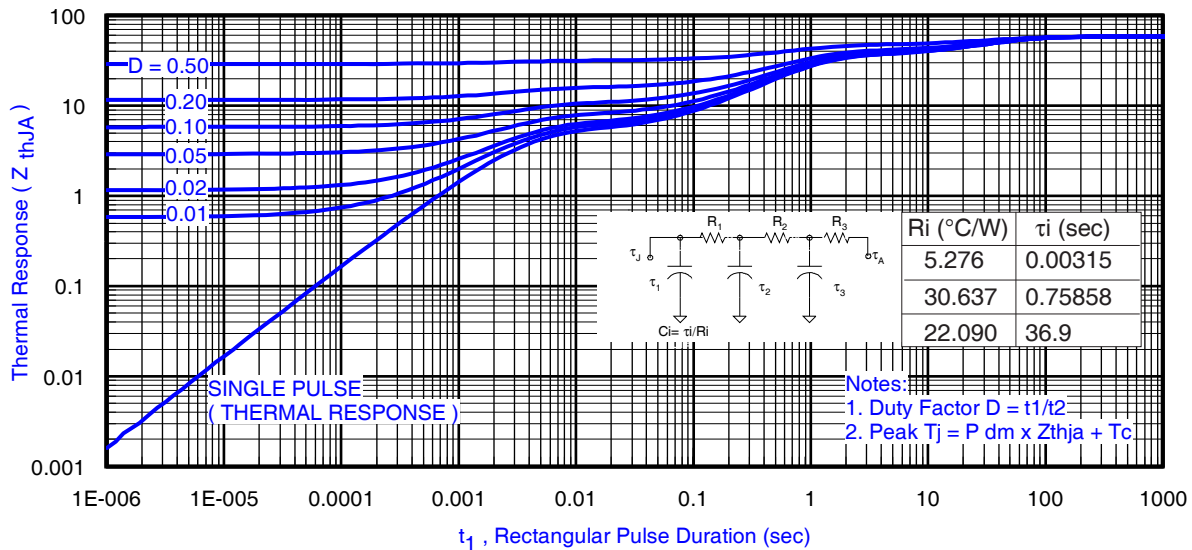
⑦ Pulse width ≤ 400μs; duty cycle ≤ 2%.

Absolute Maximum Ratings

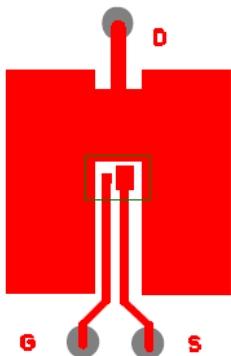
	Parameter	Max.	Units
$P_D @ T_A = 25^\circ\text{C}$	Power Dissipation ③	2.2	W
$P_D @ T_A = 70^\circ\text{C}$	Power Dissipation ③	1.4	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation ④	42	
T_P	Peak Soldering Temperature	270	$^\circ\text{C}$
T_J	Operating Junction and	-40 to + 150	
T_{STG}	Storage Temperature Range		

Thermal Resistance

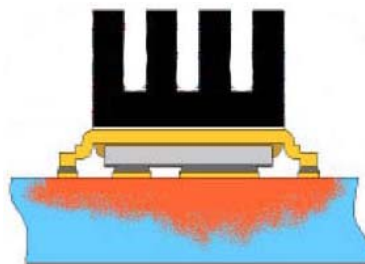
	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③⑩	—	58	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction-to-Ambient ⑧⑩	12.5	—	
$R_{\theta JA}$	Junction-to-Ambient ⑨⑩	20	—	
$R_{\theta JC}$	Junction-to-Case ④⑩	—	3.0	
$R_{\theta J-PCB}$	Junction-to-PCB Mounted	1.0	—	
	Linear Derating Factor ③	0.017		$\text{W}/^\circ\text{C}$


Fig 3. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient ③
Notes:

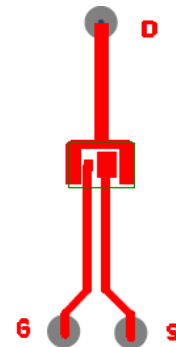
- ③ Used double sided cooling , mounting pad with large heatsink.
- ④ Mounted on minimum footprint full size board with metalized back and with small clip heatsink.
- ⑩ R_{θ} is measured at T_J of approximately 90°C .



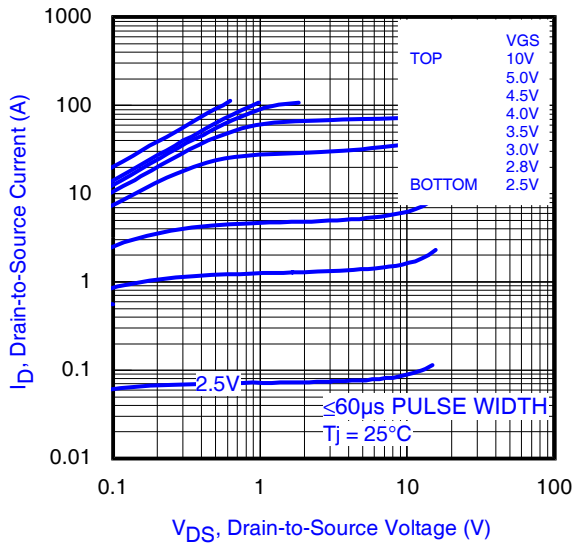
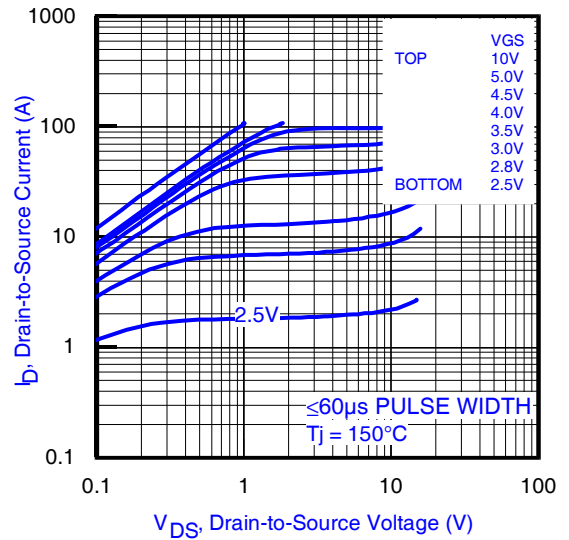
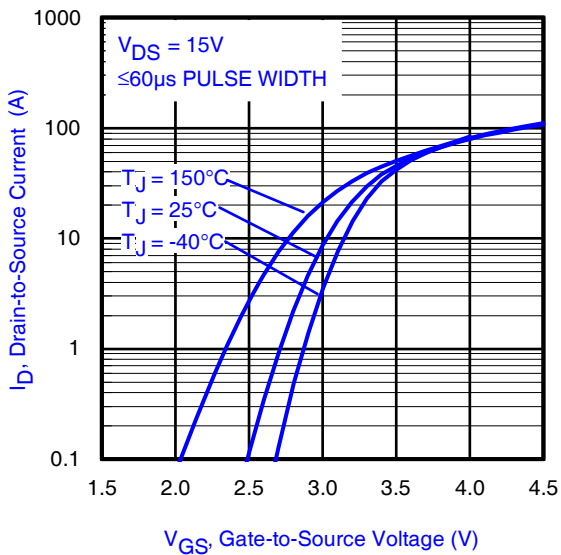
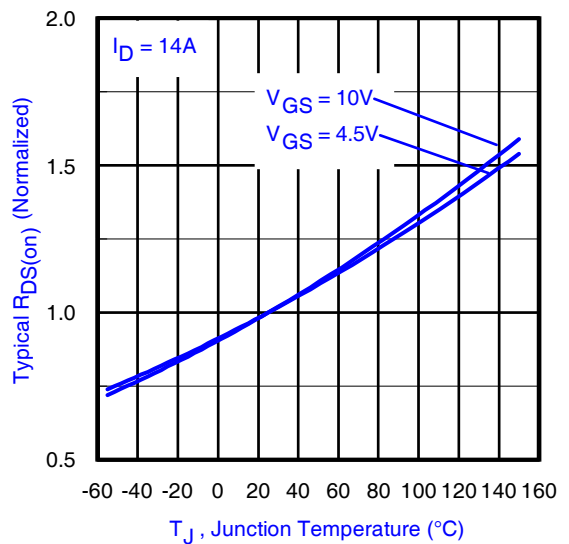
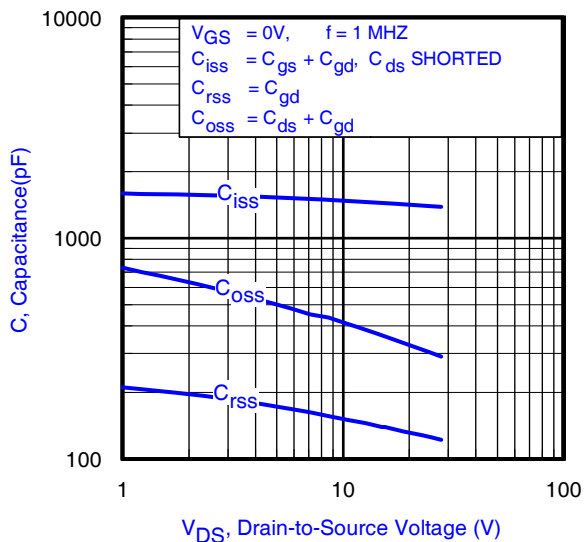
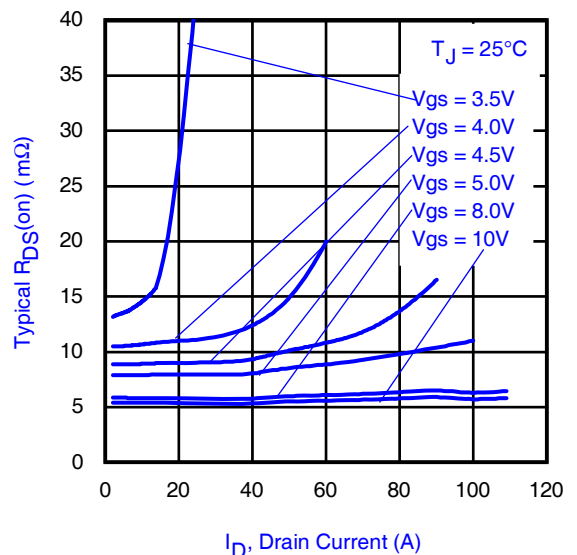
③ Surface mounted on 1 in. square Cu (still air).

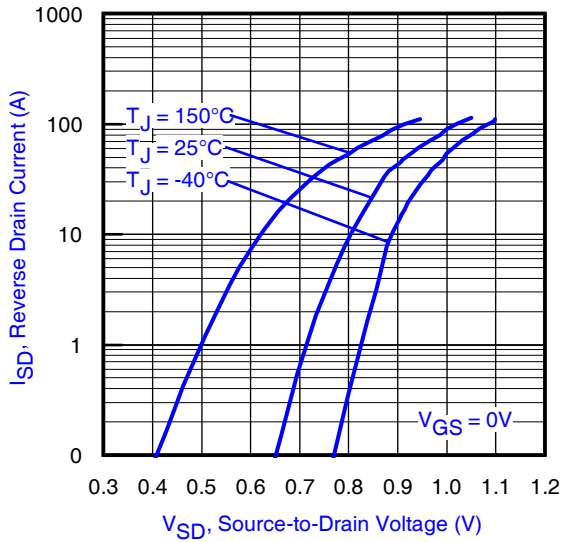
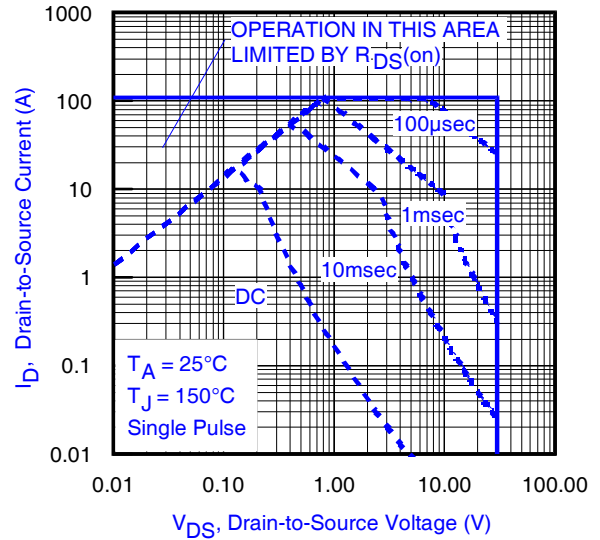
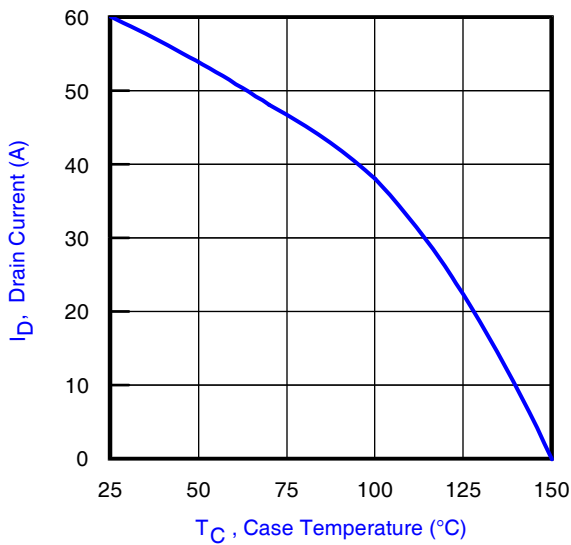
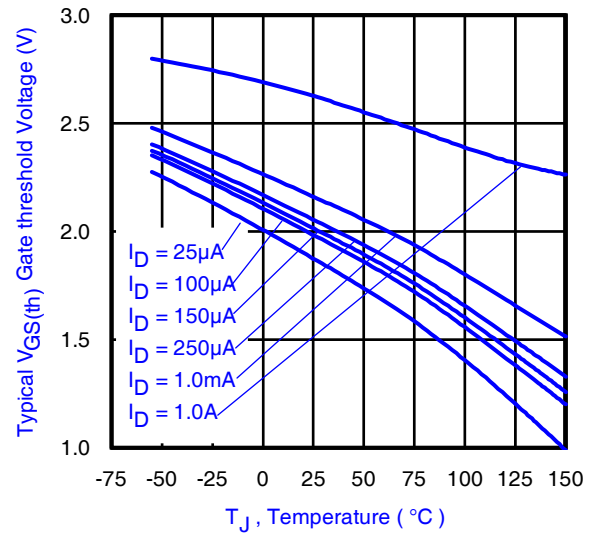
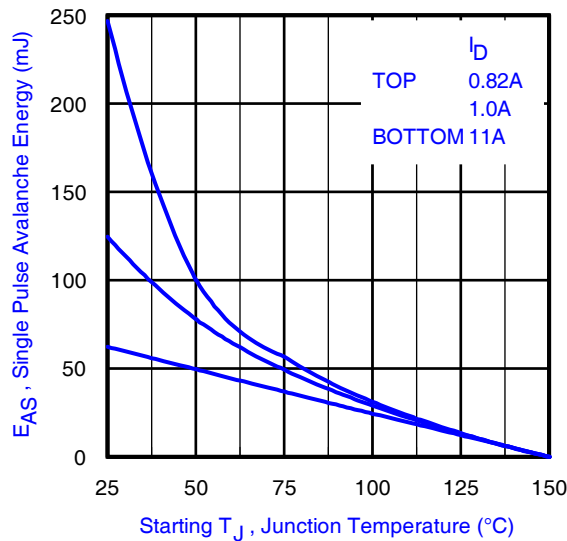


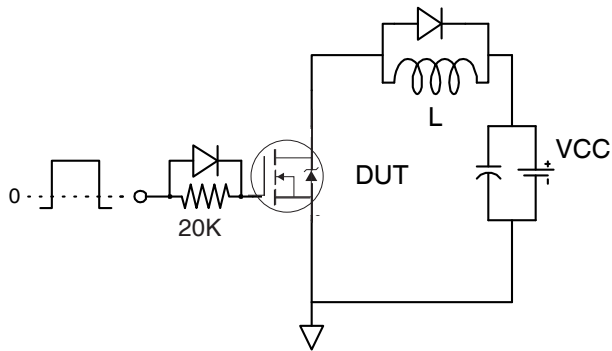
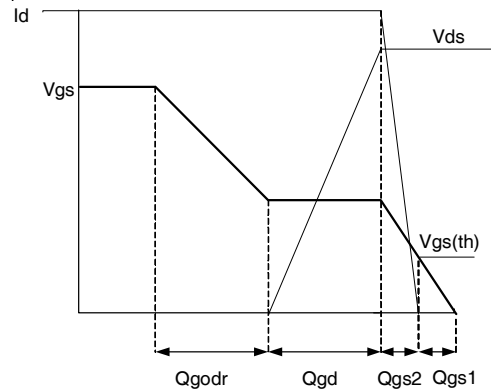
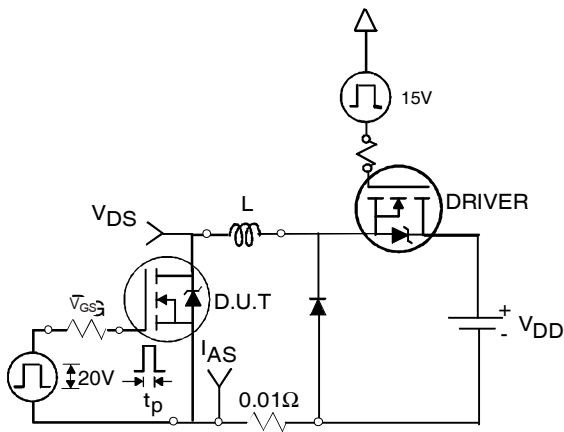
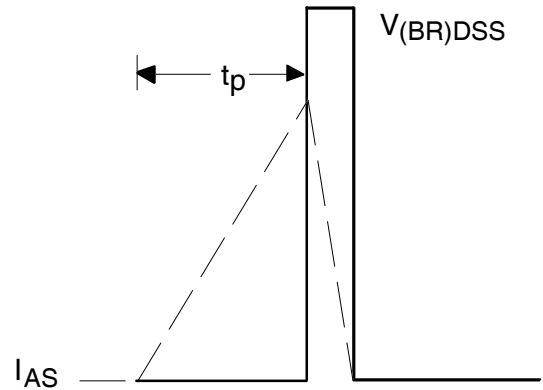
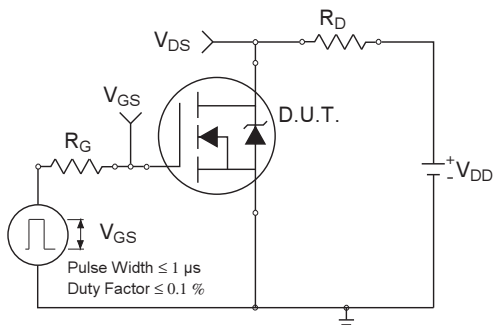
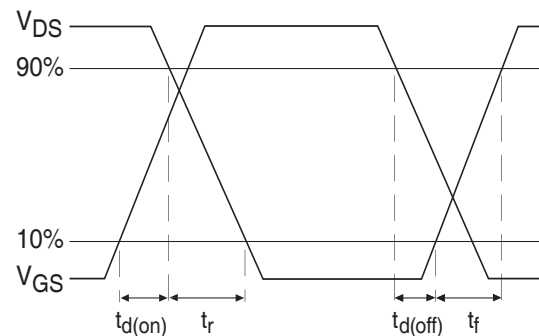
④ Mounted to a PCB with small clip heatsink (still air)



⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink (still air)


Fig 4. Typical Output Characteristics

Fig 5. Typical Output Characteristics

Fig 6. Typical Transfer Characteristics

Fig 7. Normalized On-Resistance vs. Temperature

Fig 8. Typical Capacitance vs. Drain-to-Source Voltage

Fig 9. Typical On-Resistance vs. Drain Current and Gate Voltage


Fig 10. Typical Source-Drain Diode Forward Voltage

Fig11. Maximum Safe Operating Area

Fig 12. Maximum Drain Current vs. Case Temperature

Fig 13. Typical Threshold Voltage vs. Junction Temperature

Fig 14. Maximum Avalanche Energy vs. Drain Current


Fig 15a. Gate Charge Test Circuit

Fig 15b. Gate Charge Waveform

Fig 16a. Unclamped Inductive Test Circuit

Fig 16b. Unclamped Inductive Waveforms

Fig 17a. Switching Time Test Circuit

Fig 17b. Switching Time Waveforms

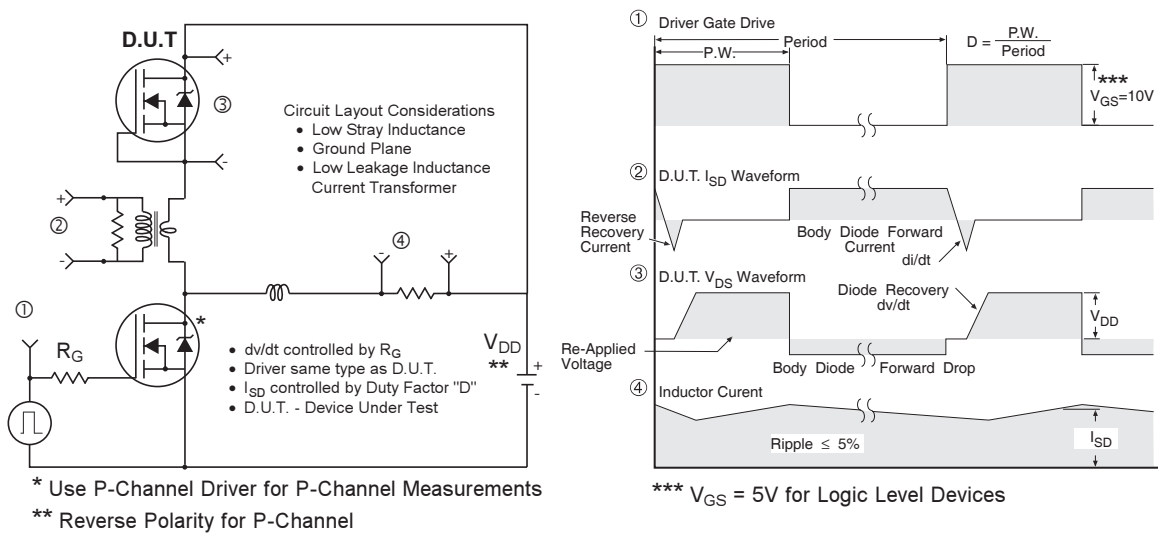
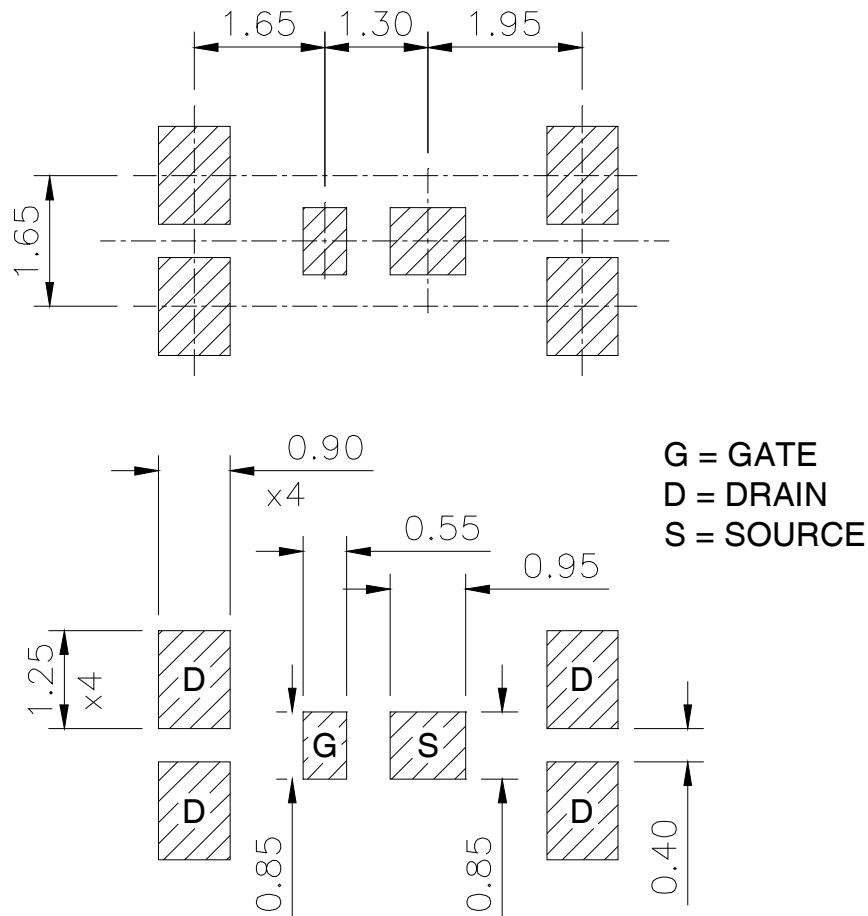


Fig 18. Diode Reverse Recovery Test Circuit for HEXFET® Power MOSFETs

DirectFET® Board Footprint, SQ Outline (Small Size Can, Q-Designation).

Please see DirectFET application note AN-1035 for all details regarding the assembly of DirectFET.

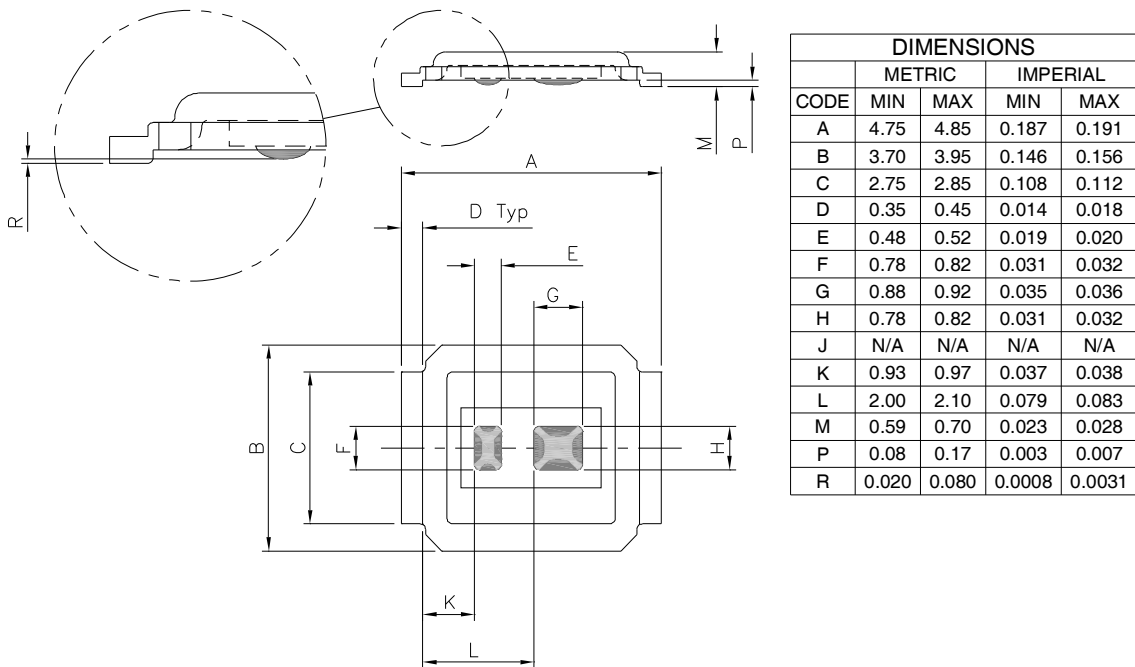
This includes all recommendations for stencil and substrate designs.



Note: For the most current drawing please refer to IR website at: <http://www.irf.com/package/>

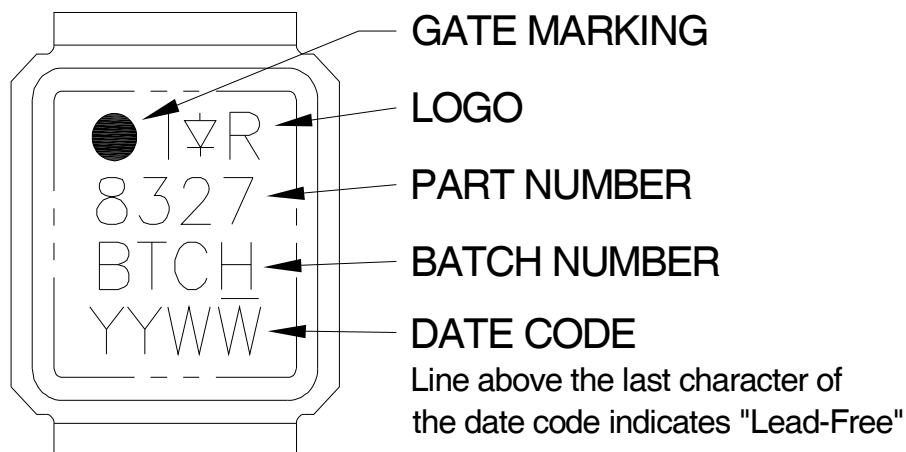
DirectFET® Outline Dimension, SQ Outline (Small Size Can, Q-Designation).

Please see DirectFET application note AN-1035 for all details regarding the assembly of DirectFET. This includes all recommendations for stencil and substrate designs.



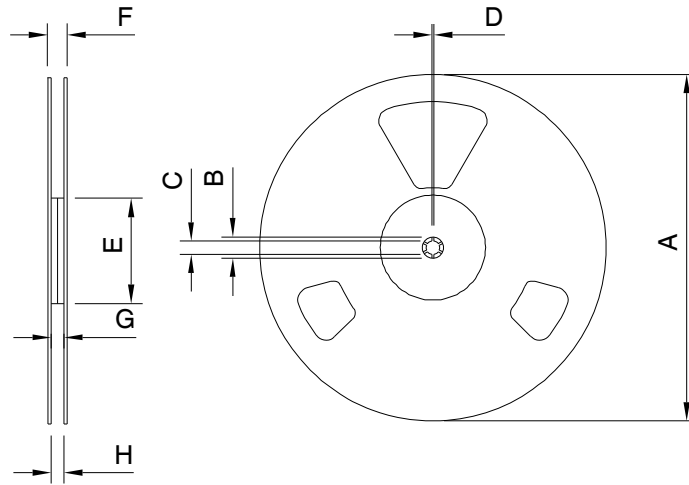
Dimensions are shown in millimeters (inches)

DirectFET® Part Marking



Note: For the most current drawing please refer to IR website at: <http://www.irf.com/package/>

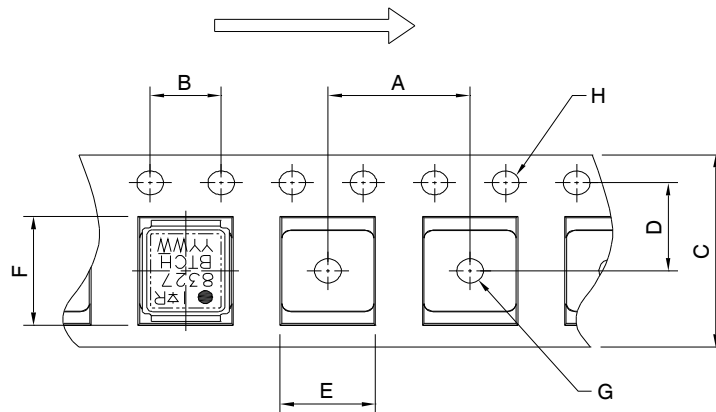
DirectFET® Tape & Reel Dimension (Showing component orientation).



NOTE: Controlling dimensions in mm Std reel quantity is 4800 parts. (ordered as IRF8327SPBF).

REEL DIMENSIONS				
STANDARD OPTION(QTY 4800)				
CODE	METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX
A	330.0	N.C	12.992	N.C
B	20.2	N.C	0.795	N.C
C	12.8	13.2	0.504	0.520
D	1.5	N.C	0.059	N.C
E	100.0	N.C	3.937	N.C
F	N.C	18.4	N.C	0.724
G	12.4	14.4	0.488	0.567
H	11.9	15.4	0.469	0.606

LOADED TAPE FEED DIRECTION



NOTE: CONTROLLING DIMENSIONS IN MM

CODE	METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX
A	7.90	8.10	0.311	0.319
B	3.90	4.10	0.154	0.161
C	11.90	12.30	0.469	0.484
D	5.45	5.55	0.215	0.219
E	4.00	4.20	0.158	0.165
F	5.00	5.20	0.197	0.205
G	1.50	N.C	0.059	N.C
H	1.50	1.60	0.059	0.063

Note: For the most current drawing please refer to IR website at: <http://www.irf.com/package/>

Qualification Information†

Qualification level	Consumer ††	
	(per JEDEC JESD47F††† guidelines)	
	Comments: This family of products has passed JEDEC's Industrial qualification. IR's Consumer qualification level is granted by extension of the higher Industrial level.	
Moisture Sensitivity Level	DFET	MSL1 (per JEDEC J-STD-020D†††)
RoHS Compliant	Yes	

† Qualification standards can be found at International Rectifier's web site
<http://www.irf.com/product-info/reliability>

†† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information:
<http://www.irf.com/whoto-call/salesrep/>

††† Applicable version of JEDEC standard at the time of product release.

Revision History

Date	Comments
5/6/2014	<ul style="list-style-type: none"> Updated ordering information to reflect the End-Of-life (EOL) of the mini-reel option (EOL notice #264). Updated data sheet based on corporate template.

Данный компонент на территории Российской Федерации

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<http://moschip.ru/get-element>

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

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